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(54) **INTEGRATED CIRCUIT AND MANUFACTURING METHOD THEREOF**

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(52) **U.S. Cl.**
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(21) Appl. No.: **15/990,807**

(57) **ABSTRACT**

(22) Filed: **May 28, 2018**

An integrated circuit includes a substrate, at least one n-type semiconductor device, and at least one p-type semiconductor device. The n-type semiconductor device is present on the substrate. The n-type semiconductor device includes a gate structure having a bottom surface and at least one sidewall. The bottom surface of the gate structure of the n-type semiconductor device and the sidewall of the gate structure of the n-type semiconductor device intersect to form an interior angle. The p-type semiconductor device is present on the substrate. The p-type semiconductor device includes a gate structure having a bottom surface and at least one sidewall. The bottom surface of the gate structure of the p-type semiconductor device and the sidewall of the gate structure of the p-type semiconductor device intersect to form an interior angle smaller than the interior angle of the gate structure of the n-type semiconductor device.

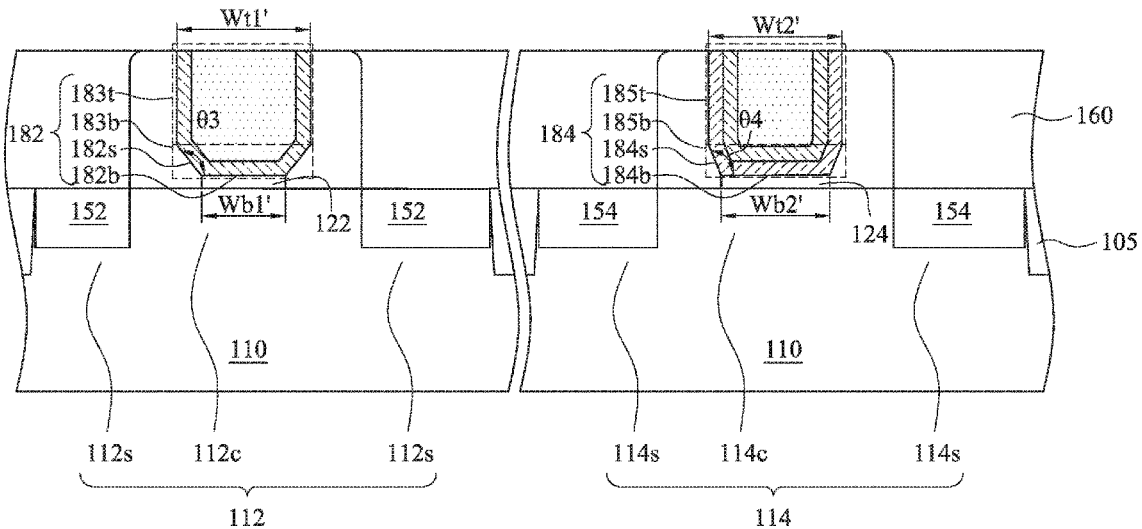
Related U.S. Application Data

(62) Division of application No. 15/074,985, filed on Mar. 18, 2016, now Pat. No. 9,985,031.

(60) Provisional application No. 62/281,459, filed on Jan. 21, 2016.

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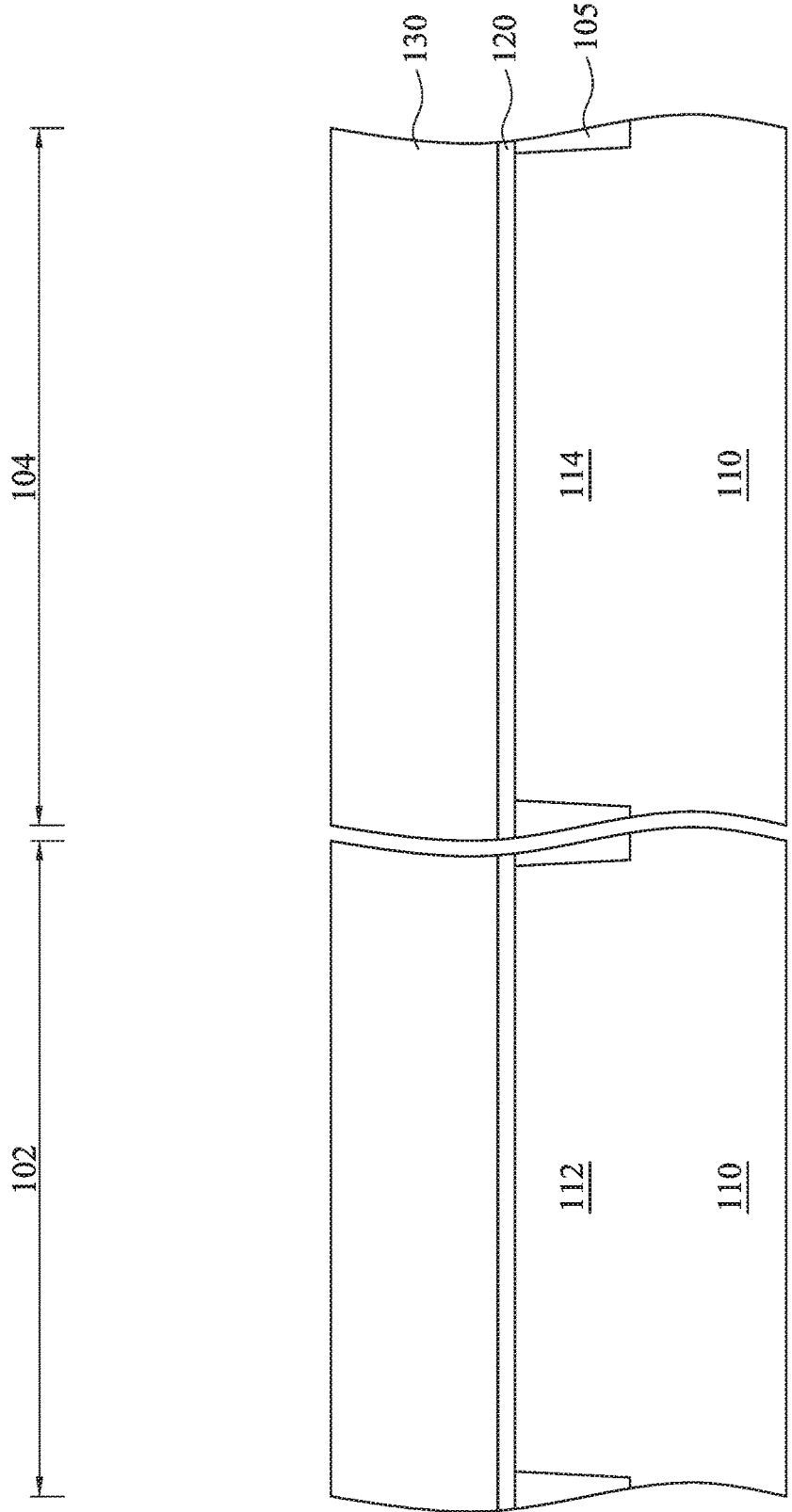


Fig. 1A

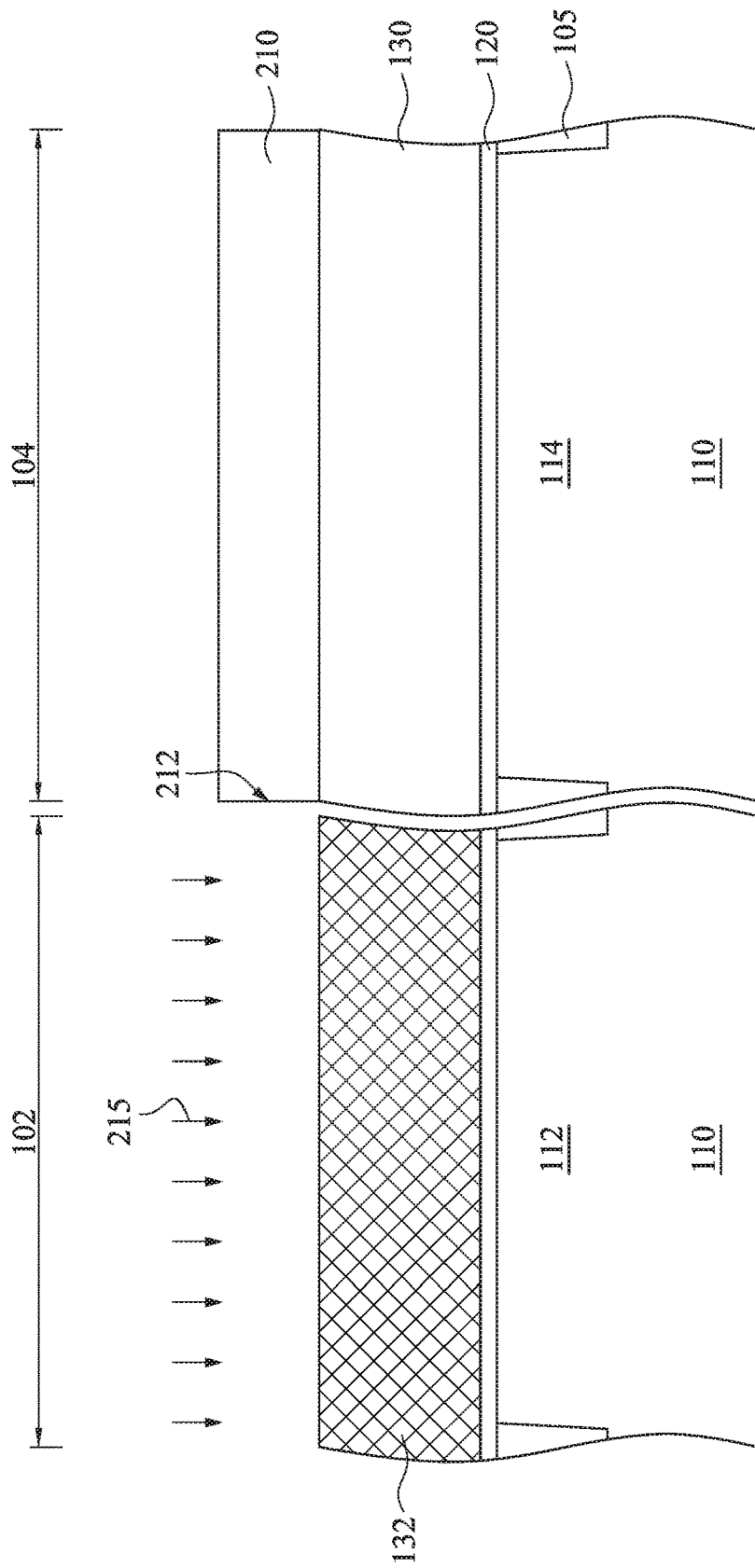


Fig. 1B

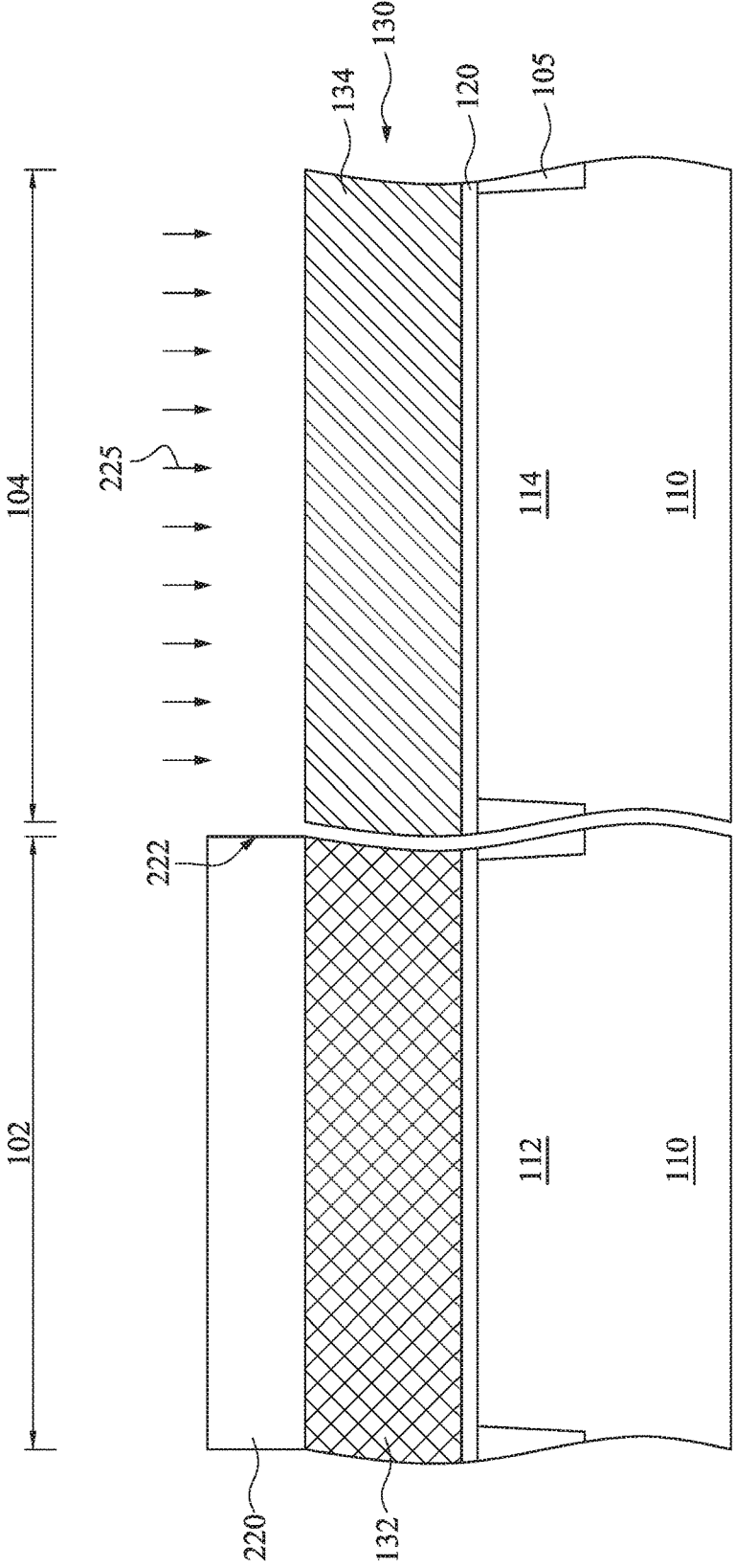


Fig. 1C

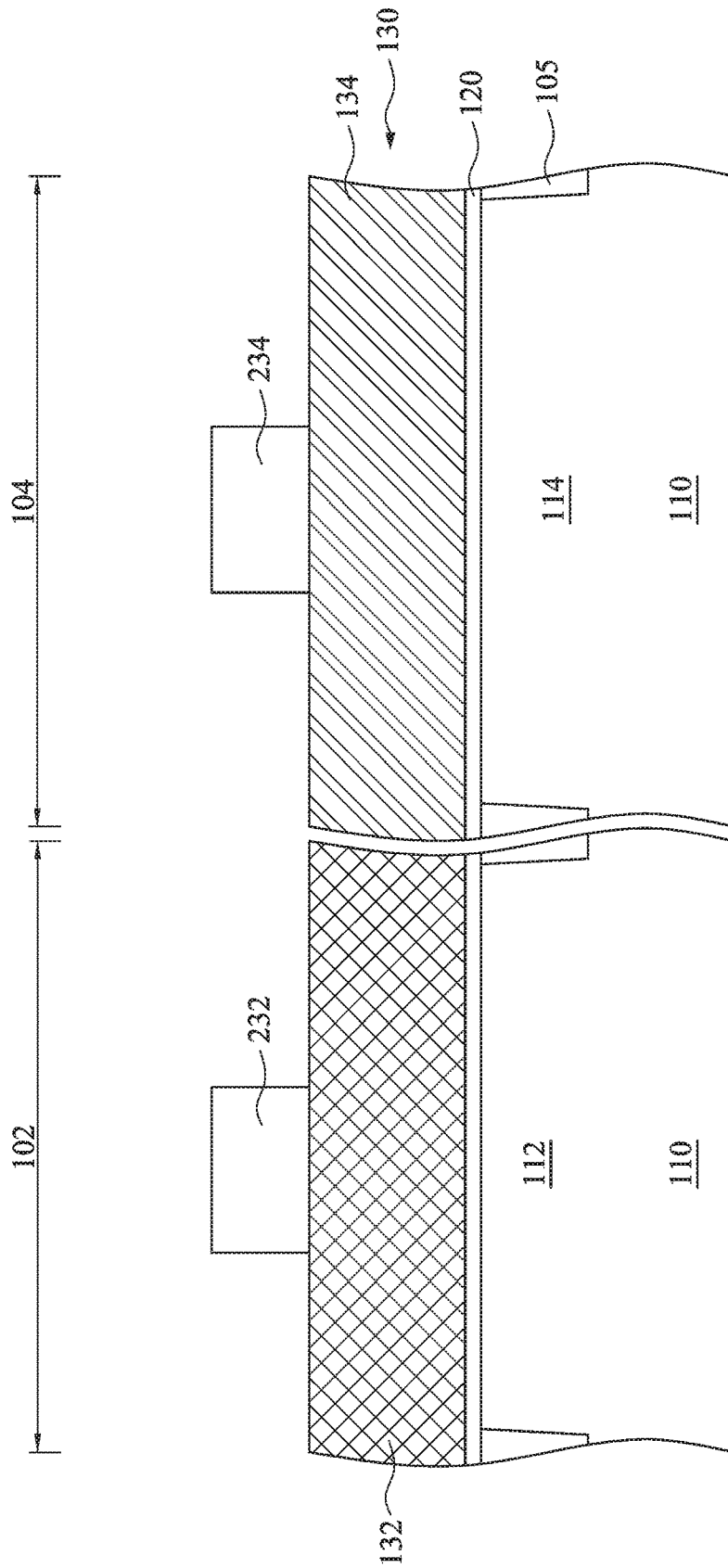


Fig. 1D

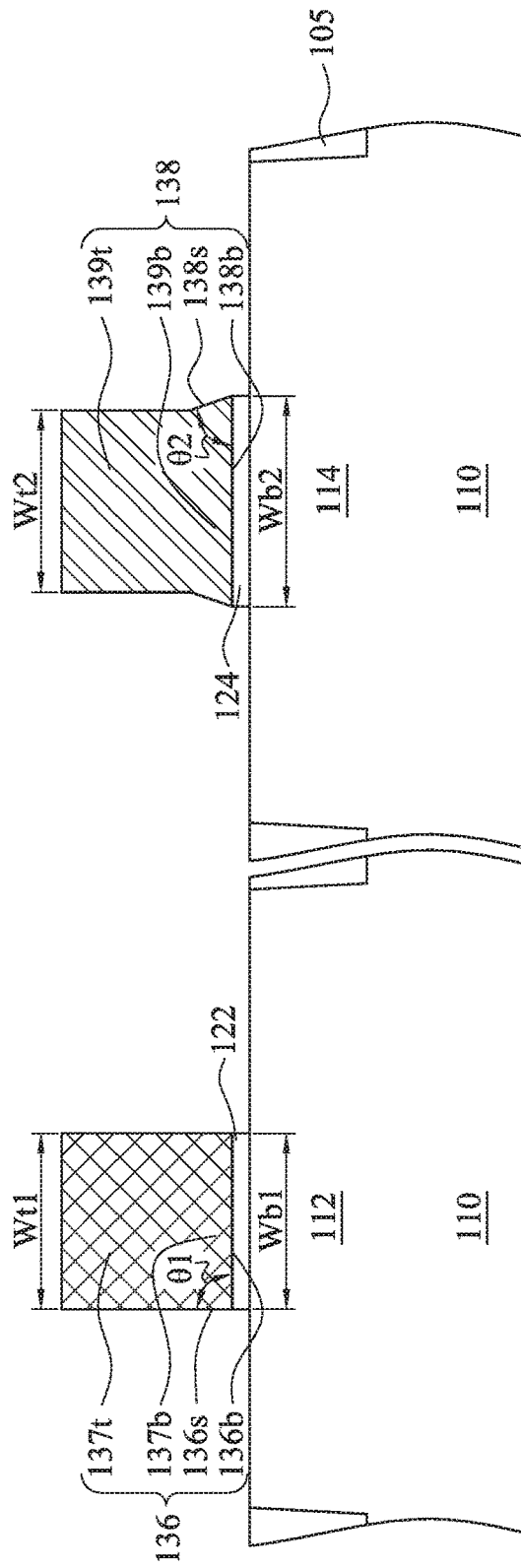


Fig. 1E

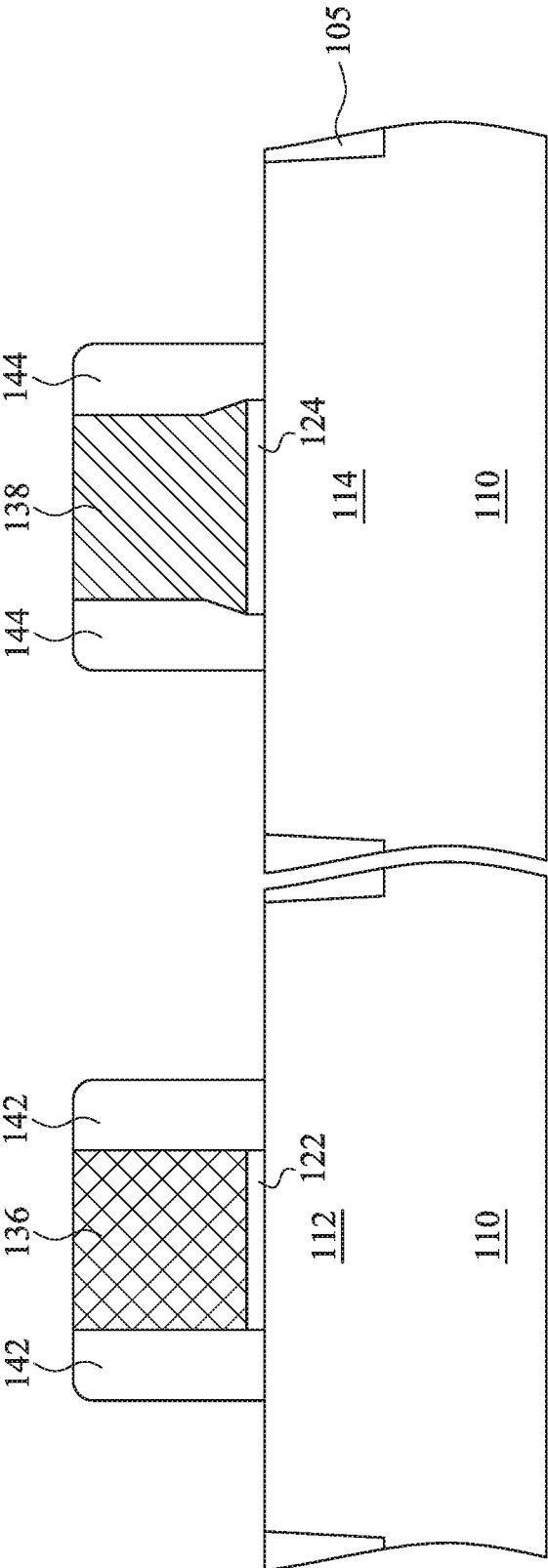


Fig. 1F

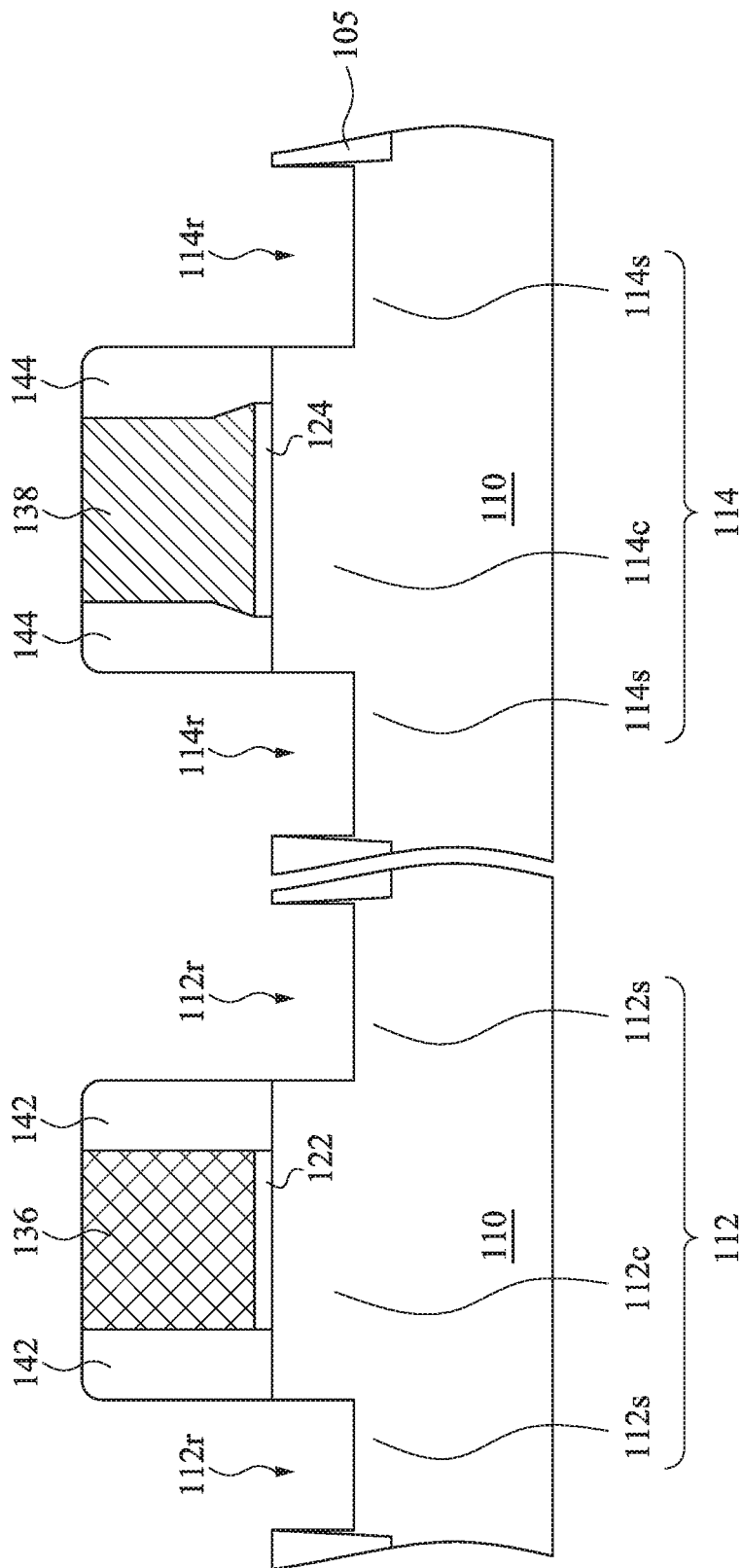


Fig. 1G

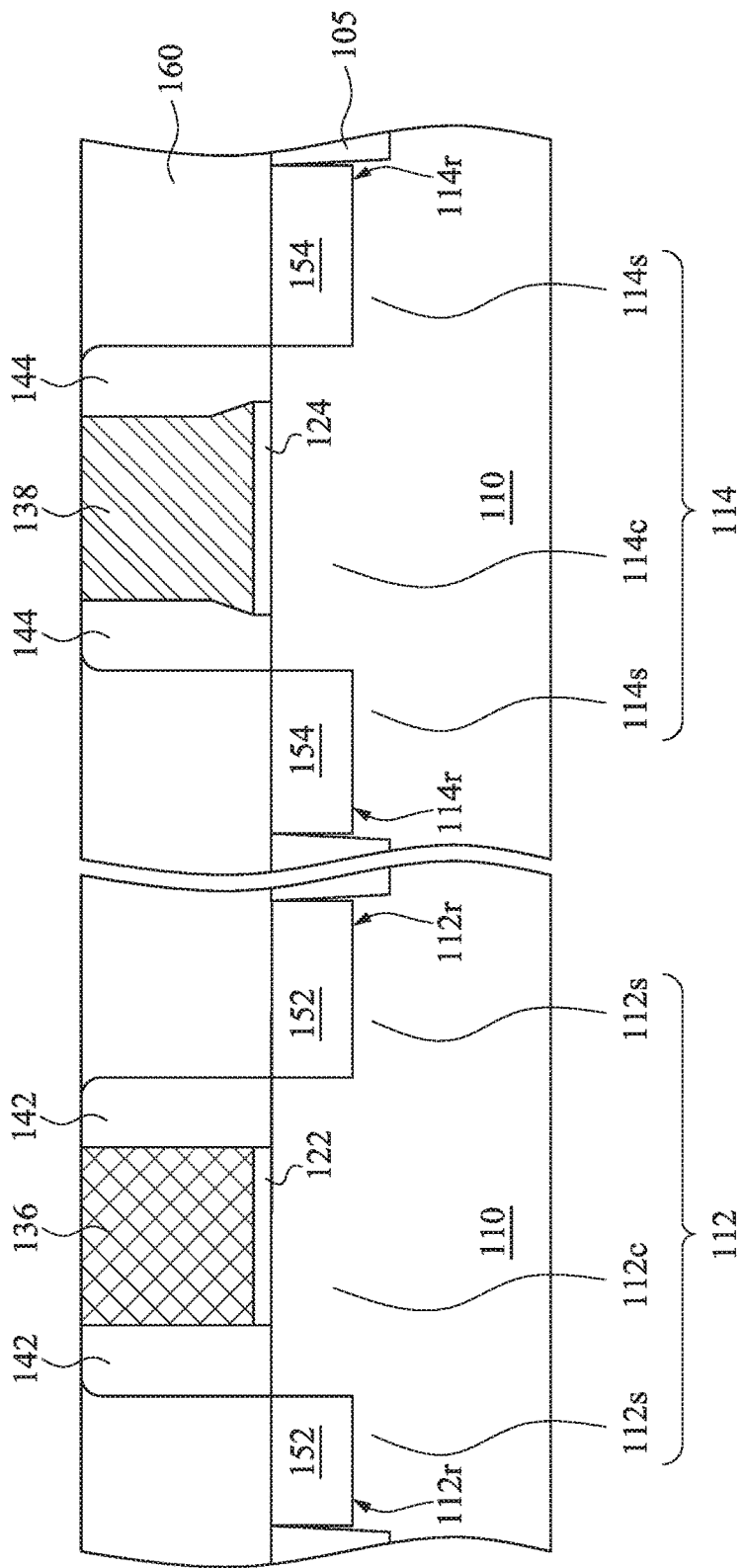


Fig. 1H

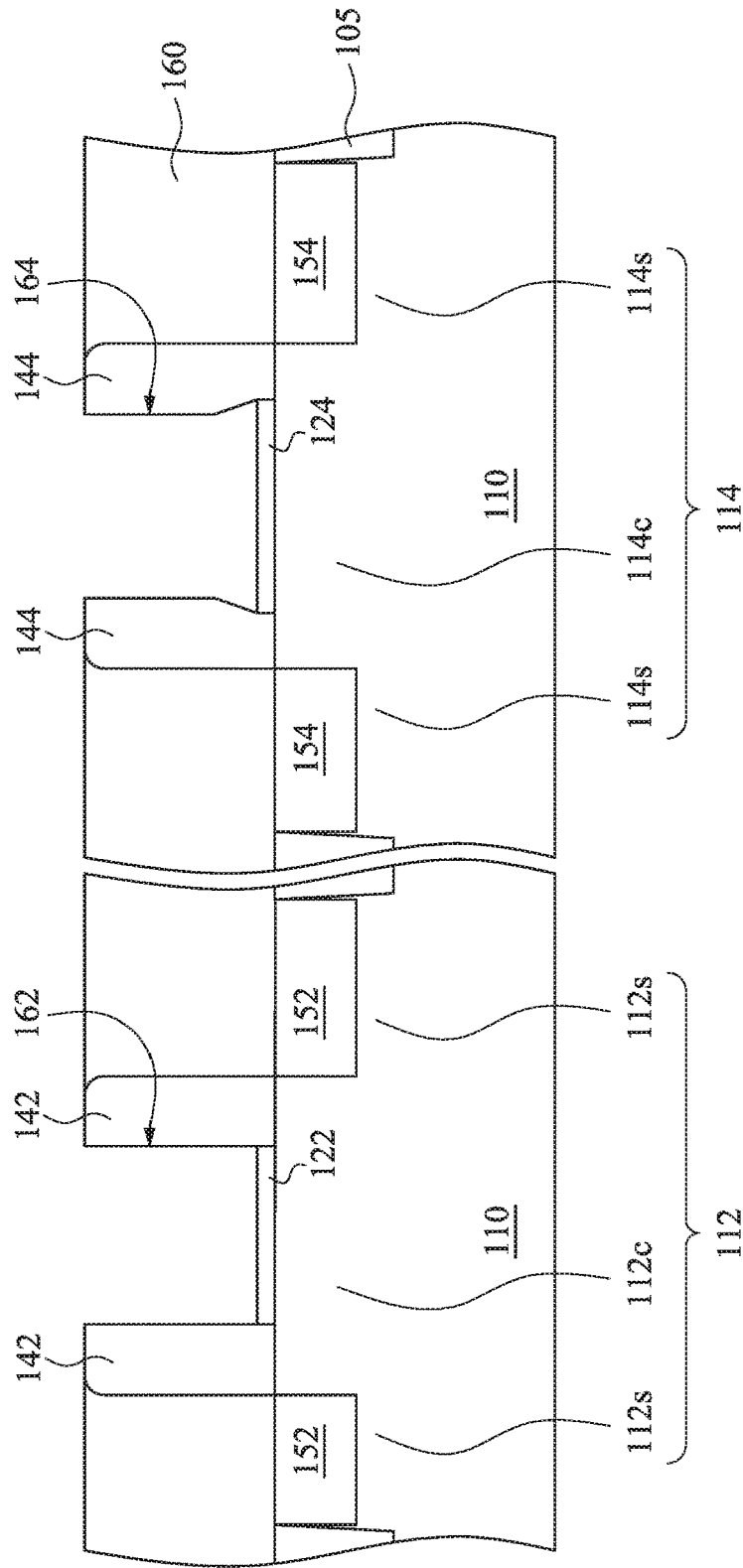


Fig. 11

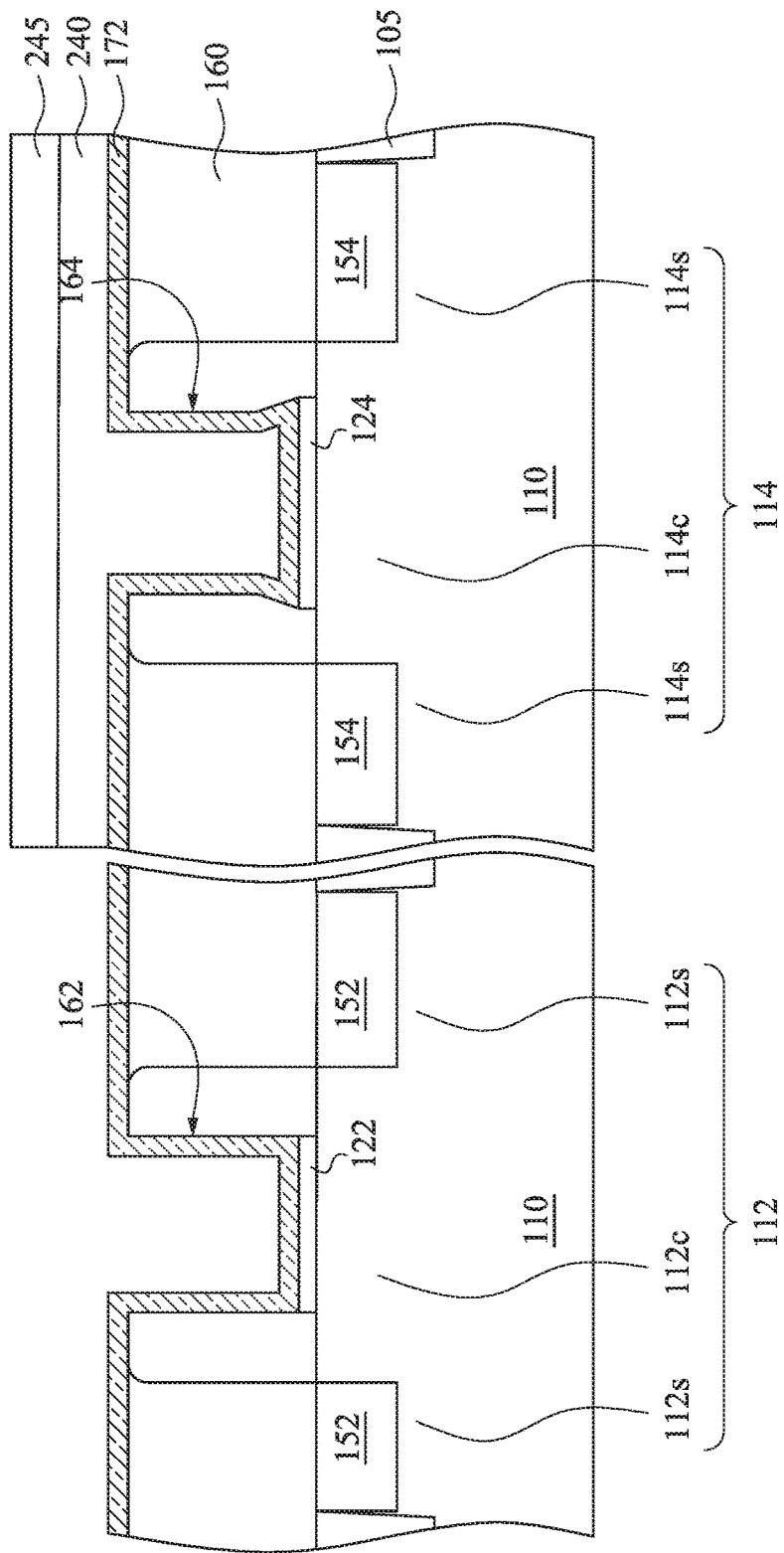


Fig. 1J

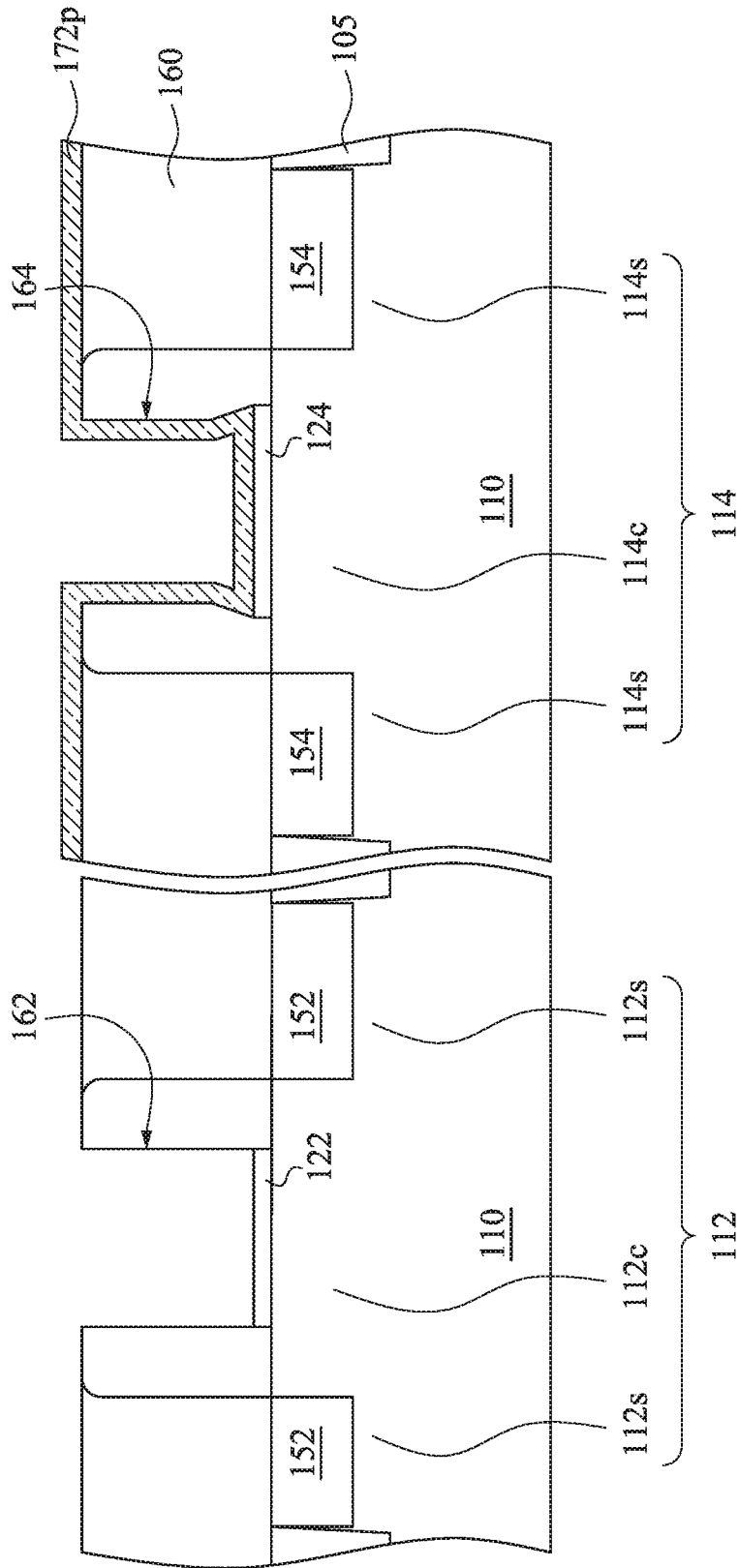


Fig. 1K

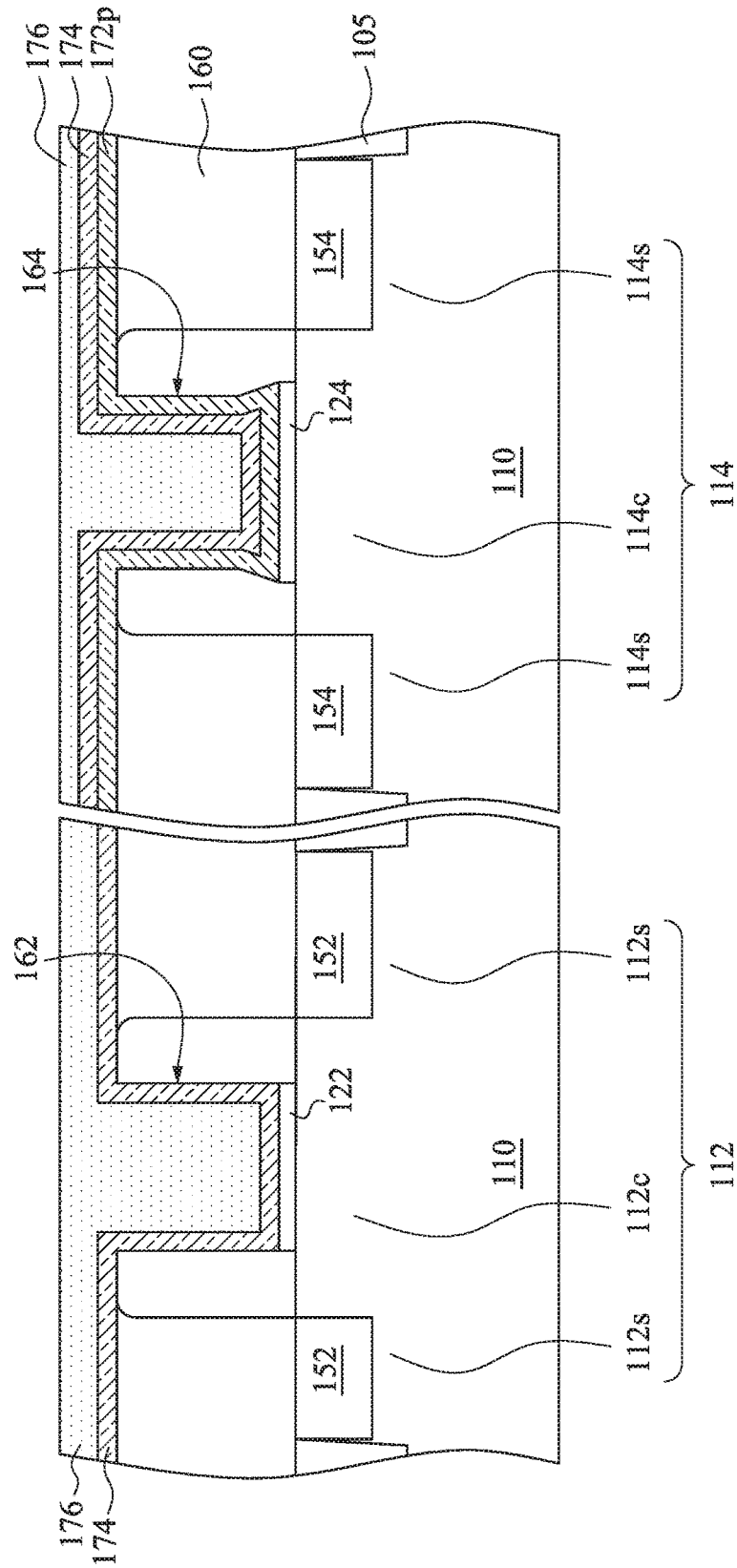


Fig. 1L

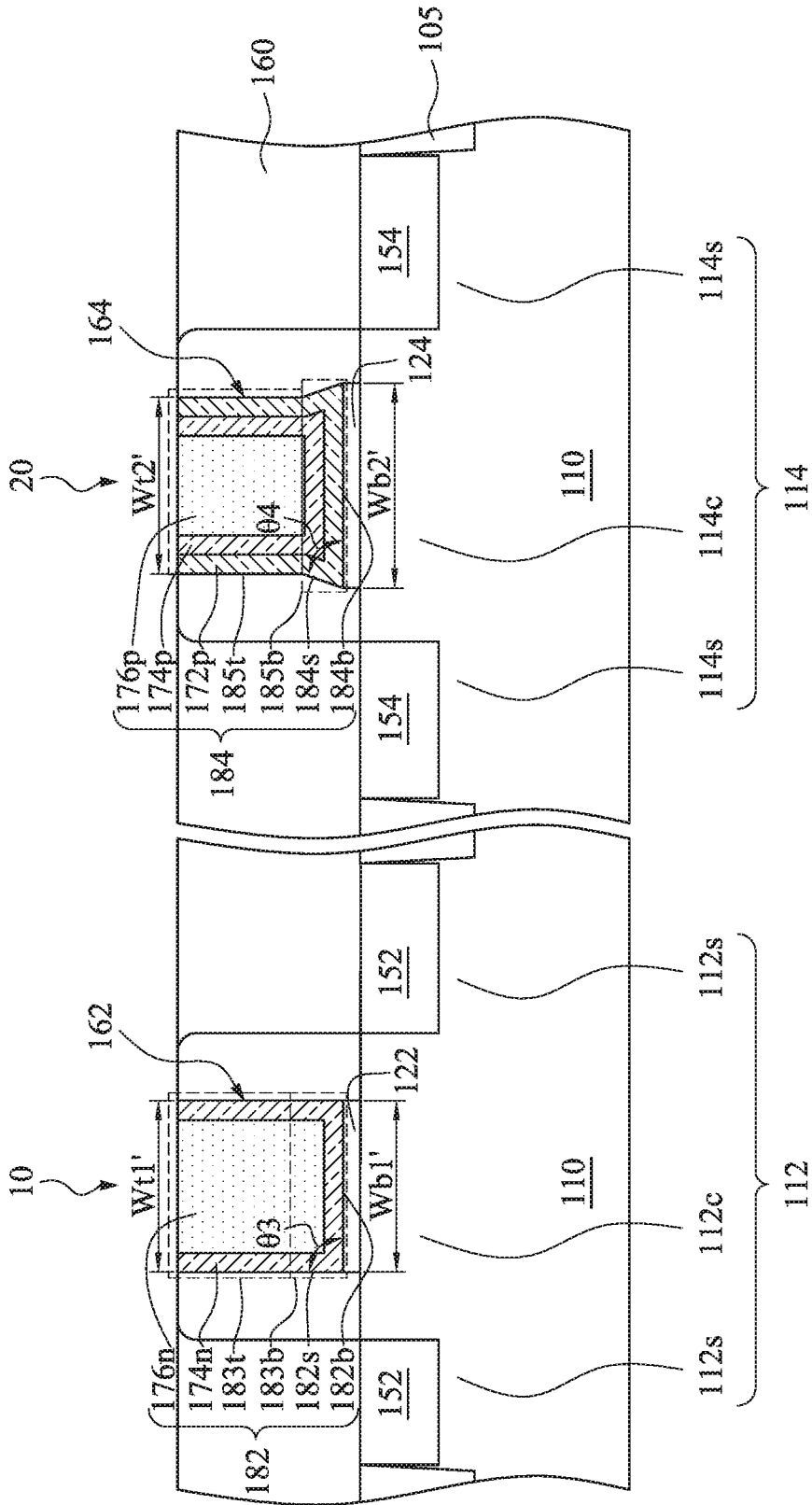


Fig. 1M

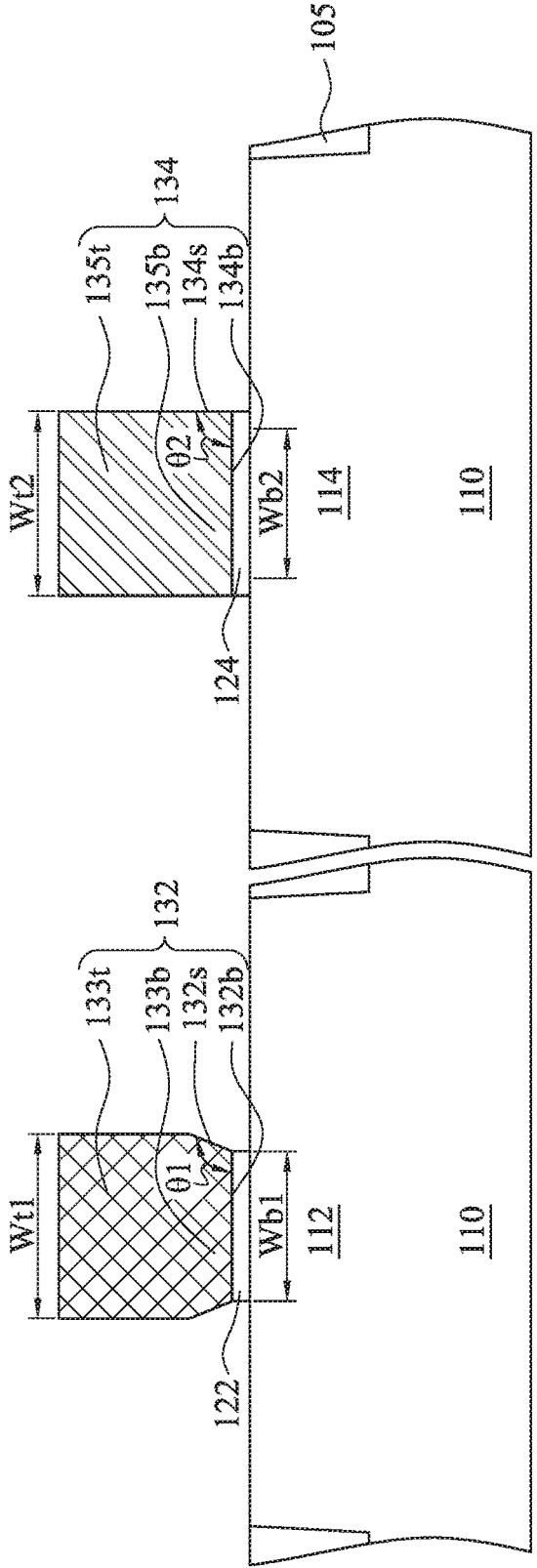


Fig. 2A

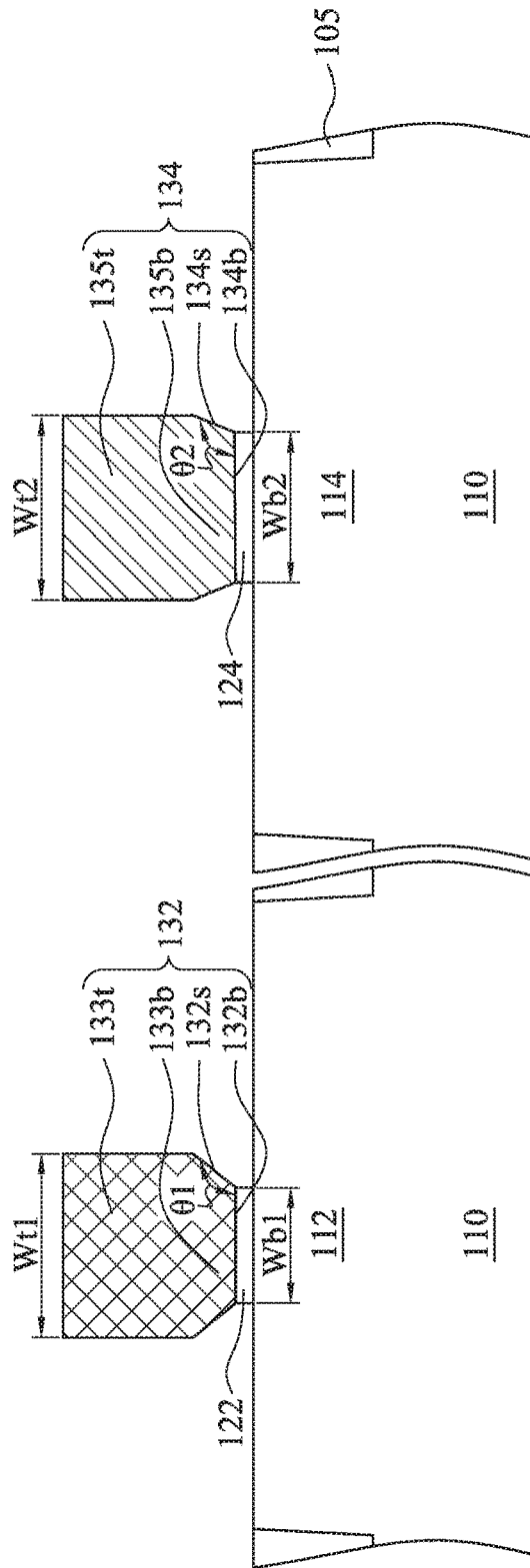


Fig. 2B

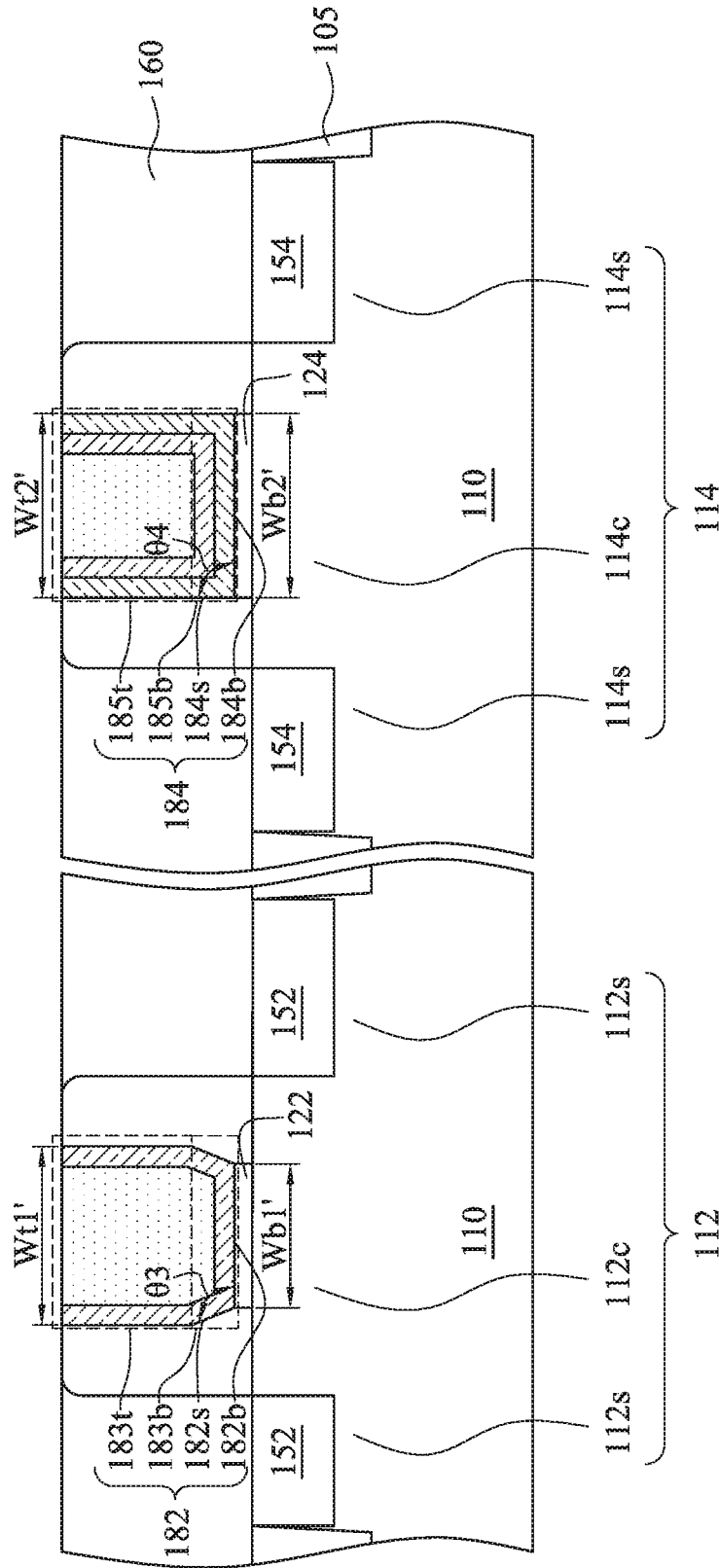


Fig. 3A

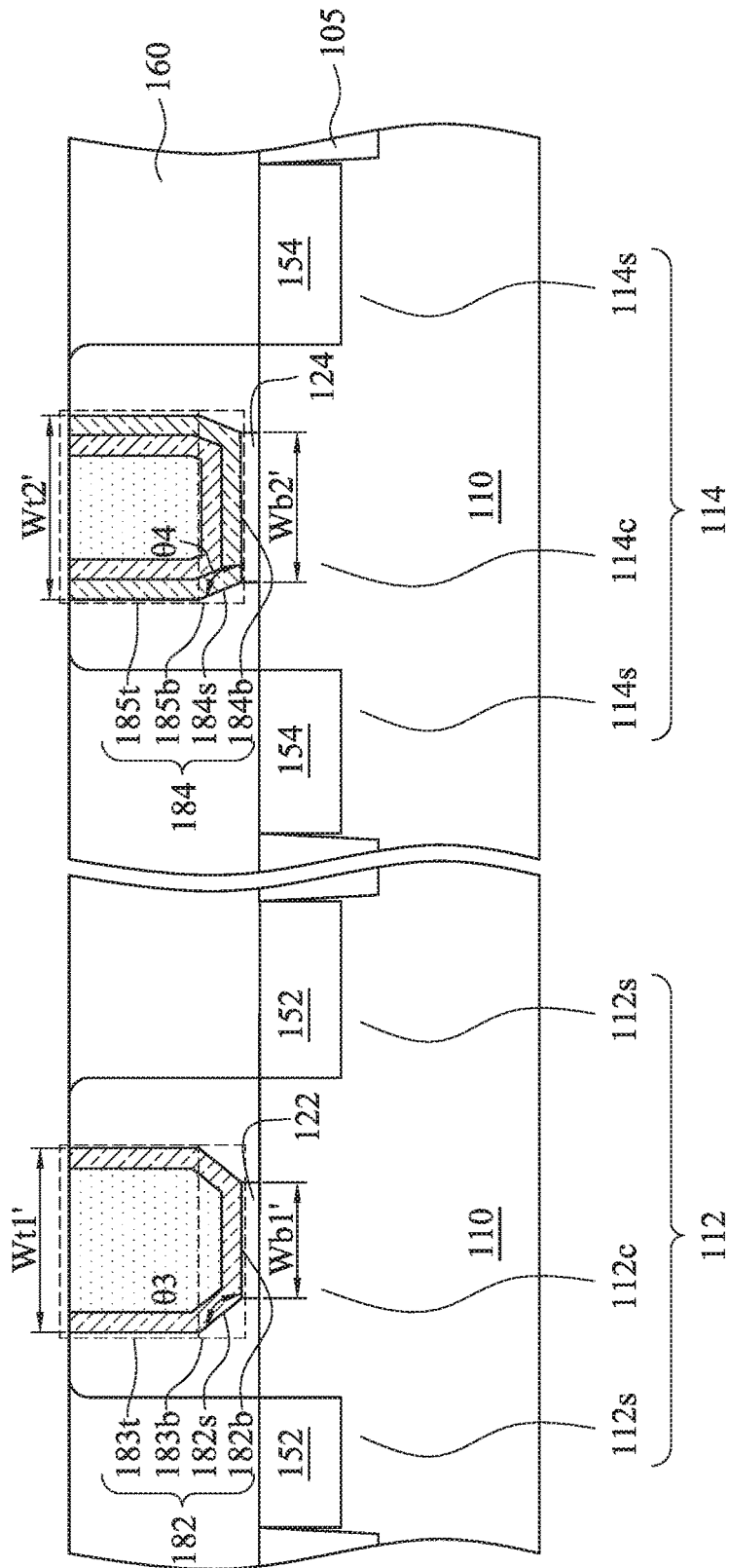


Fig. 3B

INTEGRATED CIRCUIT AND MANUFACTURING METHOD THEREOF

PRIORITY CLAIM AND CROSS-REFERENCE

[0001] This application is a divisional of and claims priority to U.S. Non-Provisional application Ser. No. 15/074,985, titled “INTEGRATED CIRCUIT AND MANUFACTURING METHOD THEREOF” and filed on Mar. 18, 2016, which claims priority to U.S. Provisional Application Ser. No. 62/281,459, titled “SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF” and filed Jan. 21, 2016. U.S. Non-Provisional Application Ser. No. 15/074,985 and U.S. Provisional Application Ser. No. 62/281,459 are incorporated herein by reference.

BACKGROUND

[0002] Semiconductor devices are small electronic components that are fabricated on a semiconductor wafer substrate. Using a variety of fabrication techniques, these devices are made and connected together to form integrated circuits. A number of integrated circuits may be found on one chip, and are capable of performing a set of useful functions in the operation of an electronic appliance. Examples of such electronic appliances are mobile telephones, personal computers, and personal gaming devices. As the size of these popular devices would imply, the components formed on a chip are small.

BRIEF DESCRIPTION OF THE DRAWINGS

[0003] Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It is noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion.

[0004] FIGS. 1A to 1M are cross-sectional views of a method for manufacturing a semiconductor device at various stages in accordance with some embodiments of the present disclosure.

[0005] FIGS. 2A and 2B are cross-sectional views of the semiconductor device at stage of FIG. 1E in accordance with some embodiments of the present disclosure.

[0006] FIGS. 3A and 3B are cross-sectional views of the semiconductor device at stage of FIG. 1M in accordance with some embodiments of the present disclosure.

DETAILED DESCRIPTION

[0007] The following disclosure provides many different embodiments, or examples, for implementing different features of the provided subject matter. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and

clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

[0008] Further, spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper” and the like, may be used herein for ease of description to describe one element or feature’s relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

[0009] Examples of devices that can be improved from one or more embodiments of the present application are semiconductor devices. Such a device, for example, is a Fin field effect transistor (FinFET) device. The following disclosure will continue with a FinFET example to illustrate various embodiments of the present application. It is understood, however, that the application should not be limited to a particular type of device.

[0010] FIGS. 1A to 1M are cross-sectional views of a method for manufacturing a semiconductor device at various stages in accordance with some embodiments of the present disclosure. Reference is made to FIG. 1A. A substrate 110 is provided. In some embodiments, the substrate 110 includes silicon. Alternatively, the substrate 110 may include germanium, silicon germanium, gallium arsenide or other appropriate semiconductor materials. Also alternatively, the substrate 110 may include an epitaxial layer. For example, the substrate 110 may have an epitaxial layer overlying a bulk semiconductor. Further, the substrate 110 may be strained for performance enhancement. For example, the epitaxial layer may include a semiconductor material different from that of the bulk semiconductor, such as a layer of silicon germanium overlying bulk silicon or a layer of silicon overlying bulk silicon germanium. Such strained substrate may be formed by selective epitaxial growth (SEG). Furthermore, the substrate 110 may include a semiconductor-on-insulator (SOI) structure. Also alternatively, the substrate 110 may include a buried dielectric layer, such as a buried oxide (BOX) layer, such as that formed by separation by implantation of oxygen (SIMOX) technology, wafer bonding, SEG, or other appropriate method.

[0011] At least one semiconductor fin 112 and at least one semiconductor fin 114 are formed on the substrate 110. In some embodiments, the semiconductor fins 112 and 114 include silicon. The semiconductor fins 112 and 114 may be formed, for example, by patterning and etching the substrate 110 using photolithography techniques. In some embodiments, a layer of photoresist material (not shown) is sequentially deposited over the substrate 110. The layer of photoresist material is irradiated (exposed) in accordance with a desired pattern (the semiconductor fins 112 and 114 in this case) and developed to remove portions of the photoresist material. The remaining photoresist material protects the underlying material from subsequent processing steps, such as etching. It should be noted that other masks, such as an oxide or silicon nitride mask, may also be used in the etching process.

[0012] An interlayer dielectric 120 is formed to cover the semiconductor fins 112 and 114 and the substrate 110. The interlayer dielectric 120 may be formed by thermal oxidation, chemical vapor deposition, sputtering, or other meth-

ods known and used in the art for forming a gate dielectric. Depending on the technique of dielectric layer formation, the thickness of the interlayer dielectric **120** on the top of the semiconductor fins **112** and **114** may be different from the thickness of the interlayer dielectric **120** on the sidewall (not shown) of the semiconductor fins **112** and **114**. The interlayer dielectric **120** may include, for example, a high-k dielectric material such as metal oxides, metal nitrides, metal silicates, transition metal-oxides, transition metal-nitrides, transition metal-silicates, oxynitrides of metals, metal aluminates, zirconium silicate, zirconium aluminate, or combinations thereof. Some embodiments may include hafnium oxide (HfO₂), hafnium silicon oxide (HfSiO), hafnium silicon oxynitride (HfSiON), hafnium tantalum oxide (HfTaO), hafnium titanium oxide (HfTiO), hafnium zirconium oxide (HfZrO), lanthanum oxide (LaO), zirconium oxide (ZrO), titanium oxide (TiO), tantalum oxide (Ta₂O₅), yttrium oxide (Y₂O₃), strontium titanium oxide (SrTiO₃, STO), barium titanium oxide (BaTiO₃, BTO), barium zirconium oxide (BaZrO), hafnium lanthanum oxide (HfLaO), lanthanum silicon oxide (LaSiO), aluminum silicon oxide (AlSiO), aluminum oxide (Al₂O₃), silicon nitride (Si₃N₄), oxynitrides (SiON), and combinations thereof. The interlayer dielectric **120** may have a multilayer structure such as one layer of silicon oxide (e.g., interfacial layer) and another layer of high-k material. The interlayer dielectric **120** may be formed using chemical vapor deposition (CVD), physical vapor deposition (PVD), atomic layer deposition (ALD), thermal oxide, ozone oxidation, other suitable processes, or combinations thereof.

[0013] A dummy gate layer **130** is formed on the interlayer dielectric **120**. The dummy gate layer **130** has at least one n-type portion **102** and at least one p-type portion **104**. For example, in FIG. 1A, the dummy gate layer **130** has one n-type portion **102** and one p-type portion **104**. The dummy gate layer **130** may be deposited by chemical vapor deposition (CVD), by sputter deposition, or by other techniques known and used in the art for depositing conductive materials. The dummy gate layer **130** may include polycrystalline-silicon (poly-Si) or poly-crystalline silicon-germanium (poly-SiGe).

[0014] Reference is made to FIG. 1B. A mask layer **210** is formed on a portion of the dummy gate layer **130** present outside the n-type portion **102** of the dummy gate layer **130**. The mask layer **210** can be a resist layer, which is also referred to as a photoresist layer, photosensitive layer, imaging layer, patterning layer, or radiation sensitive layer. The mask layer **210** includes a positive-type resist material, a negative-type resist material, other type material, or combinations thereof. The mask layer **210** is formed on the dummy gate layer **130** by a lithography process. The lithography process includes resist coating (for example, spin-on coating), soft baking, mask aligning, exposure, post-exposure baking, developing the resist, rinsing, drying (for example, hard baking), other suitable processes, or combinations thereof. Alternatively, the lithography process is implemented or replaced by other methods, such as maskless lithography, electron-beam writing, or ion-beam writing. In yet another alternative, the lithography process implements nanoimprint technology to pattern the mask layer. In some embodiments, the lithography process implements an etching process, such as a dry etching, wet etching, other etching method, or combinations thereof. A rinsing process, such as

a de-ionized (DI) water rinse, may be performed on the dummy gate layer **130** before forming the mask layer **210**.

[0015] The mask layer **210** includes an opening **212** that exposes the n-type portion **102** of the dummy gate layer **130**. In FIG. 1B, an ion implantation process (or doping process) **215** is performed on the dummy gate layer **130** using the mask layer **210** as a mask. In FIG. 1B, the ion implantation process **215** forms a doped region **132** with a plurality of first dopants. The first dopants include B, P, As, or combinations thereof.

[0016] Reference is made to FIG. 1C. The mask layer **210** (see FIG. 1B) is removed. In some embodiments, the mask layer **210** is removed by performing a wet etching process. In some embodiments, wet etch solution for the wet etching process includes a Caros solution, including sulfuric acid (H₂SO₄) and peroxide (H₂O₂). Alternatively, the mask layer **210** is removed by a chemical solution selected from O₃ water, sulfuric acid (H₂SO₄) and ozone (O₃), H₂SO₄ and H₂O₂, N-methyl-2-pyrrolidone (NMP), cyclohexanol, cyclopentanol, propylene glycol monomethyl ether (PGME), and Propylene glycol monomethyl ether acetate (PGMEA). In some other embodiment, the mask layer **210** is removed by a chemical solution selected from oxidant based solution. In some embodiments, a cleaning process is performed to clean organic residue or other residues after the removal of the mask layer **210**. The cleaning material is capable of removing the organic residue. The cleaning material may include solvent, surfactant or polymer ingredient.

[0017] Another mask layer **220** is formed on a portion of the dummy gate layer **130** present outside the p-type portion **104** of the dummy gate layer **130**. The mask layer **220** can be a resist layer, which is also referred to as a photoresist layer, photosensitive layer, imaging layer, patterning layer, or radiation sensitive layer. The mask layer **220** includes a positive-type resist material, a negative-type resist material, other type material, or combinations thereof. The mask layer **220** is formed on the dummy gate layer **130** by a lithography process. The lithography process includes resist coating (for example, spin-on coating), soft baking, mask aligning, exposure, post-exposure baking, developing the resist, rinsing, drying (for example, hard baking), other suitable processes, or combinations thereof. Alternatively, the lithography process is implemented or replaced by other methods, such as maskless lithography, electron-beam writing, or ion-beam writing. In yet another alternative, the lithography process implements nanoimprint technology to pattern the mask layer. In some embodiments, the lithography process implements an etching process, such as a dry etching, wet etching, other etching method, or combinations thereof. A rinsing process, such as a de-ionized (DI) water rinse, may be performed on the dummy gate layer **130** before forming the mask layer **220**.

[0018] The mask layer **220** includes an opening **222** that exposes the p-type portion **104** of the dummy gate layer **130**. In FIG. 1C, another ion implantation process (or doping process) **225** is performed on the dummy gate layer **130** using the mask layer **220** as a mask. In FIG. 1C, the ion implantation process **225** forms another doped region **134** with a plurality of second dopants. The second dopants include B, P, As, or combinations thereof.

[0019] Reference is made to FIG. 1D. The mask layer **220** (see FIG. 1C) is removed. In some embodiments, the mask layer **220** is removed by performing a wet etching process. In some embodiments, wet etch solution for the wet etching

process includes a Caros solution, including sulfuric acid (H_2SO_4) and peroxide (H_2O_2). Alternatively, the mask layer 220 is removed by a chemical solution selected from O_3 water, sulfuric acid (H_2SO_4) and ozone (O_3), H_2SO_4 and H_2O_2 , N-methyl-2-pyrrolidone (NMP), cyclohexanol, cyclopentanol, propylene glycol monomethyl ether (PGME), and Propylene glycol monomethyl ether acetate (PGMEA). In some other embodiment, the mask layer 220 is removed by a chemical solution selected from oxidant based solution. In some embodiments, a cleaning process is performed to clean organic residue or other residues after the removal of the mask layer 220. The cleaning material is capable of removing the organic residue. The cleaning material may include solvent, surfactant or polymer ingredient.

[0020] A patterned mask layer is then formed on the doped regions 132 and 134 of the dummy gate layer 130. The patterned mask layer includes masks 232 and 234. The mask 232 is present on the doped region 132 of the dummy gate layer 130, and the mask 234 is present on the doped region 134 of the dummy gate layer 130. The masks 232 and 234 respectively define profiles of gate structures present on the semiconductor fins 112 and 114.

[0021] Reference is made to FIG. 1E. The doped regions 132 and 134 of the dummy gate layer 130 of FIG. 1D are then patterned to respectively form a dummy gate structure 136 and a dummy gate structure 138 by using the masks 232 and 234 of FIGS. 1D. The doped regions 132 and 134 may be patterned by an etching process, such as a dry plasma etching process or a wet etching process.

[0022] After the patterning process, the masks 232 and 234 of FIG. 1D may then be removed. The portion of the interlayer dielectric 120 not covered by the dummy gate structures 136 and 138 may or may not be removed during the etching process. In the case where some interlayer dielectric 120 remains on the semiconductor fins 112 and 114 not covered by the dummy gate structures 136 and 138, the interlayer dielectric 120 may be subsequently removed by dry or wet etching to form gate dielectrics 122 and 124.

[0023] Since the doped regions 132 and 134 of the dummy gate layer 130 of FIG. 1D include different types of dopants, the etching rates of the doped regions 132 and 134 are different. Hence, when the doped regions 132 and 134 are etched together, the dummy gate structures with different profiles (i.e., the dummy gate structures 136 and 138) can be formed during the same etching process. For example, in FIG. 1E, the dummy gate structure 136 has substantially vertical sidewalls while the dummy gate structure 138 has a footing profile.

[0024] In greater detail, the dummy gate structure 136 has a bottom surface 136b and at least one sidewall 136s. The bottom surface 136b and the sidewall 136s intersect to form an interior angle θ_1 . The interior angle θ_1 is an angle inside the dummy gate structure 136. In FIG. 1E, the interior angle θ_1 is a substantially right angle. That is, the interior angle θ_1 is substantially 90 degrees. To describe from another point of view, the dummy gate structure 136 includes a top portion 137t and a bottom portion 137b disposed between the top portion 137t and the substrate 110. The top portion 137t has a width Wt1, and the bottom portion 137b has a width Wb1. The width Wb1 of the bottom portion 137b is substantially the same as the width Wt1 of the top portion 137t. The term "substantially" as used herein may be applied to modify any

quantitative representation which could permissibly vary without resulting in a change in the basic function to which it is related.

[0025] Moreover, the dummy gate structure 138 has a bottom surface 138b and at least one sidewall 138s. The bottom surface 138b and the sidewall 138s intersect to form an interior angle θ_2 . The interior angle θ_2 is an angle inside the dummy gate structure 138. In FIG. 1E, the interior angle θ_2 is an acute angle. That is, the interior angle θ_2 is smaller than 90 degrees. To describe from another point of view, the dummy gate structure 138 includes a top portion 139t and a bottom portion 139b disposed between the top portion 139t and the substrate 110. The top portion 139t has a width Wt2, and the bottom portion 139b has a width Wb2. The width Wb2 of the bottom portion 139b is greater than the width Wt2 of the top portion 139t.

[0026] However, the profile of the dummy gate structures 136 and 138 are not limited in this respect. FIGS. 2A and 2B are cross-sectional views of the semiconductor device at stage of FIG. 1E in accordance with some embodiments of the present disclosure. In FIGS. 2A and 2B, the interior angles θ_1 are obtuse angles. That is, the interior angles θ_1 are greater than 90 degrees. Furthermore, the width Wb1 of the bottom portion 137b is narrower than the width Wt1 of the top portion 137t. Hence, the dummy gate structures 136 in FIGS. 2A and 2B have notch profiles.

[0027] Moreover, in FIG. 2A, the interior angle θ_2 has a substantially right angle. That is, the interior angle θ_2 is substantially 90 degrees. Furthermore, the width Wb2 of the bottom portion 139b is substantially the same as the width Wt2 of the top portion 139t. In FIG. 2B, the interior angle θ_2 is an obtuse angle. That is, the interior angle θ_2 is greater than 90 degrees. Furthermore, the width Wb2 of the bottom portion 139b is narrower than the width Wt2 of the top portion 139t. Hence, the dummy gate structure 138 in FIG. 2B has a notch profile.

[0028] In FIGS. 1E, 2A, and 2B, the interior angle θ_1 is greater than the interior angle θ_2 . Furthermore, the widths Wb1, Wb2, Wt1, and Wt2 satisfy the relationship of $(Wb2 - Wt2) > (Wb1 - Wt1)$. Moreover, the width Wt1 of the dummy gate structure 136 is substantially the same as the width Wt2 of the dummy gate structure 138.

[0029] Reference is made to FIG. 1F. A pair of gate spacers 142 is formed on the substrate 110 and along the dummy gate structure 136, and a pair of gate spacers 144 is formed on the substrate 110 and along the dummy gate structure 138. In some embodiments, the gate spacers 142 and 144 may include silicon oxide, silicon nitride, silicon oxy-nitride, or other suitable material. The gate spacers 142 and 144 may include a single layer or multilayer structure. To form the gate spacers 142 and 144, a blanket layer may be formed on the substrate 110 by CVD, PVD, ALD, or other suitable technique. Then, an anisotropic etching is performed on the blanket layer to form the gate spacers 142 and 144 respectively on two sides of the dummy gate structures 136 and 138. In some embodiments, the gate spacers 142 and 144 are used to offset subsequently formed doped regions, such as source/drain regions. The gate spacers 142 and 144 may further be used for designing or modifying the source/drain region (junction) profile.

[0030] Reference is made to FIG. 1G. Portions of the semiconductor fins 112 and 114 exposed both by the dummy gate structures 136 and 138 and the gate spacers 142 and 144 are removed (or recessed) to form recesses 112r and 114r in

the substrate **110**. Any suitable amount of material may be removed. The remaining semiconductor fin **112** has a plurality of source/drain portions **112s** and a channel portion **112c**, and the remaining semiconductor fin **114** has a plurality of source/drain portions **114s** and a channel portion **114c**. The source/drain portions **112s** and **114s** are embedded in the substrate **110** and portions thereof are exposed by the recesses **112r** and **114r**. The channel portions **112c** and **114c** are respectively disposed under the dummy gate structures **136** and **138**.

[0031] Removing portions of the semiconductor fins **112** and **114** may include forming a photoresist layer or a capping layer (such as an oxide capping layer) over the structure of FIG. 1F, patterning the photoresist or capping layer to have openings that expose a portion of the semiconductor fins **112** and **114**, and etching back material from the semiconductor fins **112** and **114**. In some embodiments, the semiconductor fins **112** and **114** can be etched using a dry etching process. Alternatively, the etching process is a wet etching process, or combination dry and wet etching process. Removal may include a lithography process to facilitate the etching process. The lithography process may include photoresist coating (e.g., spin-on coating), soft baking, mask aligning, exposure, post-exposure baking, developing the photoresist, rinsing, drying (e.g., hard baking), other suitable processes, or combinations thereof. Alternatively, the lithography process is implemented or replaced by other methods, such as maskless photolithography, electron-beam writing, and ion-beam writing. In yet some other embodiments, the lithography process could implement nanoimprint technology. In some embodiments, a pre-cleaning process may be performed to clean the recesses **112r** and **114r** with HF or other suitable solution.

[0032] Reference is made to FIG. 1H. A plurality of epitaxy structures **152** and **154** are respectively formed in the recesses **112r** and **114r** and on the source/drain portions **112s** and **114s** of the semiconductor fins **112** and **114**. The epitaxy structures **152** and **154** may be formed using one or more epitaxy or epitaxial (epi) processes, such that Si features, SiGe features, and/or other suitable features can be formed in a crystalline state on the source/drain portions **112s** and **114s** of the semiconductor fins **112** and **114**. In some embodiments, the lattice constant of the epitaxy structures **152** and **154** are different from the lattice constant of the semiconductor fins **112** and **114**, and the epitaxy structures **152** and **154** are strained or stressed to enable carrier mobility of the semiconductor device and enhance the device performance. The epitaxy processes include CVD deposition techniques (e.g., vapor-phase epitaxy (VPE) and/or ultra-high vacuum CVD (UHV-CVD)), molecular beam epitaxy, and/or other suitable processes. The epitaxy process may use gaseous and/or liquid precursors, which interact with the composition of the source/drain portions **112s** and **114s** of the semiconductor fins **112** and **114** (e.g., silicon). Thus, a strained channel can be achieved to increase carrier mobility and enhance device performance. The epitaxy structures **152** and **154** may be in-situ doped. The doping species include p-type dopants, such as boron or BF₂; n-type dopants, such as phosphorus or arsenic; and/or other suitable dopants including combinations thereof. If the epitaxy structures **152** and **154** are not in-situ doped, a second implantation process (i.e., a junction implant process) is performed to dope the epitaxy structures **152** and **154**. One or more annealing processes may be performed to activate the epi-

taxy structures **152** and **154**. The annealing processes include rapid thermal annealing (RTA) and/or laser annealing processes.

[0033] Then, a dielectric layer **160** is formed at outer sides of the gate spacers **142** and **144** and on the substrate **110**. The dielectric layer **160** includes silicon oxide, oxynitride or other suitable materials. The dielectric layer **160** includes a single layer or multiple layers. The dielectric layer **160** is formed by a suitable technique, such as CVD or ALD. A chemical mechanical planarization (CMP) process may be applied to remove excessive dielectric layer **160** and expose the top surface of the dummy gate structures **132** and **134** to a subsequent dummy gate removing process.

[0034] Reference is made to FIG. 1I, the dummy gate structures **136** and **138** (see FIG. 1H) are removed to form an opening **162** with the gate spacers **142** as its sidewall and an opening **164** with the gate spacers **144** as its sidewall. The openings **162** and **164** have different profiles. Or, the opening **164** has a larger accommodate window than the opening **162**. In some embodiments, the gate dielectrics **122** and **124** are removed as well. Alternatively, in some embodiments, the dummy gate structures **136** and **138** are removed while the gate dielectrics **122** and **124** retains as shown in FIG. 1I. The dummy gate structures **136** and **138** (and the gate dielectrics **122** and **124**) may be removed by dry etch, wet etch, or a combination of dry and wet etch. For example, a wet etch process may include exposure to a hydroxide containing solution (e.g., ammonium hydroxide), deionized water, and/or other suitable etchant solutions.

[0035] Reference is made to FIG. 1J. A protection layer (not shown) and a p-type work function material **172** can be formed over the structure shown in FIG. 1I. The protection layer, for example TaN, may protect the underlying structure during a later process of defining the p-type work function metallic layer **172p** (see FIG. 1K). The p-type work function material **172** can provide a desired work function value for a metal gate structure of a p-type semiconductor device **20** (see FIG. 1M). The protection material and the p-type work function material **172** can be formed by suitable process, such as atomic layer deposition (ALD), chemical vapor deposition (CVD), physical vapor deposition (PVD), remote plasma CVD (RPCVD), plasma enhanced CVD (PECVD), metal organic CVD (MOCVD), sputtering, plating, other suitable processes, and/or combinations thereof. In some embodiments, the p-type work function material **172** can be made of TiN, Co, WN, or TaC.

[0036] A dielectric material **240**, e.g. spin-on-glass (SOG), can be formed, covering a portion of the p-type work function material **172** and filling the opening **164**. A photoresist **245** can be defined over the dielectric material **240**. The dielectric material **240** and/or the photoresist **245** can be provided for patterning the p-type work function material **172** for the p-type semiconductor device **20**. The dielectric material **240** and the photoresist **245** can be defined by, for example, a spin-on process, a photolithographic process, and an etch process.

[0037] Reference is made to FIG. 1K. A portion of the p-type work function material **172** that is not covered by the dielectric material **240** and the photoresist **240** of FIG. 1J can be removed, defining the p-type work function metallic layer **172p**. After defining the p-type work function metallic layer **172p**, the dielectric material **240** and the photoresist **245** of FIG. 1J can be removed by a wet etch process, a dry

etch process, and/or combinations thereof, exposing the p-type work function metallic layer 172p.

[0038] Reference is made to FIG. 1L. An n-type work function material 174 can be formed over the structure shown in FIG. 1K. The n-type work function material 174 can provide a desired work function value for a metal gate structure of an n-type semiconductor device 10 (see FIG. 1M). The n-type work function material 174 can be formed by suitable process, such as atomic layer deposition (ALD), chemical vapor deposition (CVD), physical vapor deposition (PVD), remote plasma CVD (RPCVD), plasma enhanced CVD (PECVD), metal organic CVD (MOCVD), sputtering, plating, other suitable processes, and/or combinations thereof. In some embodiments, the n-type work function material 174 can be made of Ti, Al, or TiAl.

[0039] The remaining openings 162 and 164 are then filled with a metal layer 176. In some embodiments, the metal layer 176 includes tungsten (W). The metal layer 176 is deposited by ALD, PVD, CVD, or other suitable process. In some other embodiments, the metal layer 176 includes aluminum (Al), copper (Cu) or other suitable conductive material.

[0040] Reference is made to FIG. 1M. In some embodiments, a CMP process is applied to remove excessive the p-type work function metallic layer 172p, the n-type work function material 174 and the metal layer 176 of FIG. 1L to provide a substantially planar top surface for the p-type work function metallic layer 172p, the n-type work function metallic layers 174n and 174p and the metal layers 176n and 176p. The remaining n-type work function metallic layers 174n and the metal layer 176n form a metal gate structure 182 present in the opening 162, and the remaining p-type work function metallic layer 172p, the n-type work function metallic layers 174p, and the metal layer 176p form a metal gate structure 184 present in the opening 162. It is noted that the formation of the metal gate structures 182 and 184 mentioned above is illustrative, and should not limit the claimed scope of the present disclosure. A person having ordinary skill in the art may select a suitable formation process for the metal gate structures 182 and 184 according to actual situations.

[0041] In FIG. 1M, the semiconductor fin 112, the epitaxy structures 152, and the metal gate structure 182 (or the dummy gate structure 136 of FIG. 1E) form the n-type semiconductor device 10, and the semiconductor fin 114, the epitaxy structures 154, and the metal gate structure 184 (or the dummy gate structure 138 of FIG. 1E) form the p-type semiconductor device 20. In FIG. 1M, both of the n-type semiconductor device 10 and the p-type semiconductor device 20 are finFETs, and the n-type semiconductor device 10 and the p-type semiconductor device 20 can form a complementary metal-oxide-semiconductor (CMOS) device.

[0042] In FIG. 1M, since the opening 164 has a larger accommodate window than the opening 162, more layers or materials can be present in the opening 164. For example, in FIG. 1M, the metal gate structure 184 includes at least three layers (i.e., the p-type work function metallic layer 172p, the n-type work function metallic layers 174p, and the metal layer 176p), and the metal gate structure 182 includes at least two layers (i.e., the n-type work function metallic layers 174n and the metal layer 176n). With such configuration, the electrical properties, such as the on current (Ion)

and the off current (Ioff), of the n-type semiconductor device 10 and the p-type semiconductor device 20 can be improved.

[0043] In FIG. 1M, the metal gate structure 182 has a bottom surface 182b and at least one sidewall 182s. The bottom surface 182b and the sidewall 182s intersect to form an interior angle θ_3 . The interior angle θ_3 is an angle inside the metal gate structure 182. In FIG. 1M, the interior angle θ_3 is a substantially right angle. That is, the interior angle θ_3 is substantially 90 degrees. To describe from another point of view, the metal gate structure 182 includes a top portion 183t and a bottom portion 183b disposed between the top portion 183t and the substrate 110. The top portion 183t has a width Wt1', and the bottom portion 183b has a width Wb1'. The width Wb1' of the bottom portion 183b is substantially the same as the width Wt1' of the top portion 183t.

[0044] However, the profile of the metal gate structure 182 is not limited in this respect. Reference is made to FIGS. 3A and 3B. In FIGS. 3A and 3B, the interior angles θ_3 are obtuse angles. That is, the interior angle θ_3 is greater than 90 degrees. Furthermore, the width Wb1' of the bottom portion 183b is narrower than the width Wt1' of the top portion 183t. Hence, the dummy gate structures 182 in FIGS. 3A and 3B have notch profiles.

[0045] Moreover, in FIG. 1M, the metal gate structure 184 has a footing profile. In greater detail, the metal gate structure 184 has a bottom surface 184b and at least one sidewall 184s. The bottom surface 184b and the sidewall 184s intersect to form an interior angle θ_4 . The interior angle θ_4 is an angle inside the metal gate structure 184. In FIG. 1M, the interior angle θ_4 is an acute angle. That is, the interior angle θ_4 is less than 90 degrees. To describe from another point of view, the metal gate structure 184 includes a top portion 185t and a bottom portion 185b disposed between the top portion 185t and the substrate 110. The top portion 185t has a width Wt2', and the bottom portion 185b has a width Wb2'. The width Wb2' of the bottom portion 185b is greater than the width Wt2' of the top portion 185t.

[0046] However, the profile of the metal gate structure 184 is not limited in this respect. FIGS. 3A and 3B are cross-sectional views of the semiconductor device at stage of FIG. 1M in accordance with some embodiments of the present disclosure. In FIG. 3A, the interior angle θ_4 is a substantially right angle. That is, the interior angle θ_4 is substantially 90 degrees. Furthermore, the width Wb2' of the bottom portion 185b is substantially the same as the width Wt2' of the top portion 185t. In FIG. 3B, the interior angle θ_4 is an obtuse angle. That is, the interior angle θ_4 is greater than 90 degrees. Furthermore, the width Wb2' of the bottom portion 185b is narrower than the width Wt2' of the top portion 185t. Hence, the metal gate structure 184 in FIG. 3B has a notch profile.

[0047] In FIGS. 1M, 3A, and 3B, the interior angle θ_3 is greater than the interior angle θ_4 . Furthermore, the widths Wb1', Wb2', Wt1', and Wt2' satisfy the relationship of $(Wb2'-Wt2') > (Wb1'-Wt1')$. Moreover, the width Wt1' of the metal gate structure 182 is substantially the same as the width Wt2' of the metal gate structure 184.

[0048] According to the aforementioned embodiments, the profiles gate structures (such as the dummy gate structures and/or the metal gate structures) of the n-type semiconductor device and the p-type semiconductor device can be different by doping different dopants into the dummy gate layer and then performing an etching process. With this configuration, the accommodate window of the opening of

the p-type semiconductor device, and more layer can be present thereof. Therefore, the electrical properties (such as Ion and Ioff) of the n-type semiconductor device and the p-type semiconductor device can be improved.

[0049] According to some embodiments, an integrated circuit includes a substrate, at least one n-type semiconductor device, and at least one p-type semiconductor device. The n-type semiconductor device is present on the substrate. The n-type semiconductor device includes a gate structure having a bottom surface and at least one sidewall. The bottom surface of the gate structure of the n-type semiconductor device and the sidewall of the gate structure of the n-type semiconductor device intersect to form an interior angle. The p-type semiconductor device is present on the substrate. The p-type semiconductor device includes a gate structure having a bottom surface and at least one sidewall. The bottom surface of the gate structure of the p-type semiconductor device and the sidewall of the gate structure of the p-type semiconductor device intersect to form an interior angle smaller than the interior angle of the gate structure of the n-type semiconductor device.

[0050] According to some embodiments, an integrated circuit includes a substrate, at least one n-type semiconductor device, and at least one p-type semiconductor device. The n-type semiconductor device is present on the substrate. The n-type semiconductor device includes a first gate structure. The first gate structure includes a top portion and a bottom portion present between the top portion and the substrate. The top portion has a first top width, and the bottom portion has a first bottom width. The p-type semiconductor device is present on the substrate. The p-type semiconductor device includes a second gate structure. The second gate structure includes a top portion and a bottom portion disposed between the top portion and the substrate. The top portion has a second top width, and the bottom portion has a second bottom width. The first gate structure and the second gate structure substantially satisfy:

[0051] $(Wb1 - Wt1) > (Wb2 - Wt2)$, wherein Wb1 is the first bottom width of the bottom portion of the first gate structure, Wt1 is the first top width of the top portion of the first gate structure, Wb2 is the second bottom width of the bottom portion of the second gate structure, and Wt2 is the second top width of the top portion of the second gate structure.

[0052] According to some embodiments, a method for manufacturing an integrated circuit includes forming a gate layer on a substrate. The gate layer has a first portion and a second portion. The first portion of the gate layer is doped with a plurality of first dopants while the second portion of the gate layer is undoped with the first dopants. At least the first portion and the second portion of the gate layer are patterned to respectively form a first gate structure and a second gate structure.

[0053] The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may

make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

What is claimed is:

1. A method for manufacturing an integrated circuit, the method comprising:

forming a gate layer on a substrate, the gate layer having a first portion and a second portion;

doping the first portion of the gate layer with first dopants while leaving the second portion of the gate layer undoped with the first dopants; and

patterning the first portion of the gate layer to form a first gate structure and patterning the second portion of the gate layer to form a second gate structure.

2. The method of claim 1, comprising:

doping the second portion of the gate layer with a plurality of second dopants, wherein the second dopants are different than the first dopants.

3. The method of claim 2, wherein the second dopants comprise B, P, As, or combinations thereof.

4. The method of claim 1, wherein patterning the first portion of the gate layer to form a first gate structure and patterning the second portion of the gate layer to form a second gate structure comprises:

patterning the first portion of the gate layer to form the first gate structure having a first cross-sectional profile, and

patterning the second portion of the gate layer to form the second gate structure having a second cross-sectional profile different than the first cross-sectional profile.

5. The method of claim 1, wherein the first dopants comprise B, P, As, or combinations thereof.

6. The method of claim 1, comprising:

forming a first spacer and a second spacer, wherein the first gate structure is disposed between the first spacer and the second spacer;

removing the first gate structure to define an opening between the first spacer and the second spacer; and

forming a metal gate structure in the opening.

7. The method of claim 6, comprising:

forming a p-type work function material layer in the opening prior to forming the metal gate structure.

8. The method of claim 1, comprising:

forming a first spacer and a second spacer, wherein the first gate structure is disposed between the first spacer and the second spacer;

forming a third spacer and a fourth spacer, wherein the second gate structure is disposed between the third spacer and the fourth spacer;

removing the first gate structure to define a first opening between the first spacer and the second spacer; and

removing the second gate structure to define a second opening between the third spacer and the fourth spacer.

9. The method of claim 8, comprising:

forming a p-type work function material layer in the first opening and the second opening;

removing the p-type work function material layer from the first opening; and

forming an n-type work function material layer in the first opening after the p-type work function material layer is removed from the first opening.

- 10.** The method of claim **9**, comprising:
forming the n-type work function material layer in the second opening over the p-type work function material layer.
- 11.** The method of claim **10**, comprising:
forming a first metal gate structure in the first opening and a second metal gate structure in the second opening over the n-type work function material layer.
- 12.** A method for manufacturing an integrated circuit, comprising:
forming a gate layer over a substrate;
forming a first mask over a first portion of the gate layer and doping a second portion of the gate layer that is not masked by the first mask using first dopants;
removing the first mask;
forming a second mask over the second portion of the gate layer and doping the first portion of the gate layer that is not masked by the second mask using second dopants; and
patterning the first portion of the gate layer to form a first gate structure and patterning the second portion of the gate layer to form a second gate structure, wherein the first gate structure has a first cross-sectional profile and the second gate structure has a second cross-sectional profile due to the first portion of the gate layer comprising the second dopants and the second portion of the gate layer comprising the first dopants.
- 13.** The method of claim **12**, comprising:
forming a first spacer and a second spacer, wherein the first gate structure is disposed between the first spacer and the second spacer;
removing the first gate structure to define an opening; and forming a gate structure in the opening.
- 14.** The method of claim **12**, comprising:
forming a first spacer and a second spacer, wherein the first gate structure is disposed between the first spacer and the second spacer;
forming a third spacer and a fourth spacer, wherein the second gate structure is disposed between the third spacer and the fourth spacer;
removing the first gate structure to define a first opening between the first spacer and the second spacer; and removing the second gate structure to define a second opening between the third spacer and the fourth spacer.
- 15.** The method of claim **14**, comprising:
forming a p-type work function material layer in the first opening and the second opening;
removing the p-type work function material layer from the first opening; and
forming an n-type work function material layer in the first opening after the p-type work function material layer is removed from the first opening.
- 16.** The method of claim **15**, comprising:
forming the n-type work function material layer in the second opening over the p-type work function material layer.
- 17.** The method of claim **16**, comprising:
forming a first metal gate structure in the first opening and a second metal gate structure in the second opening over the n-type work function material layer.
- 18.** A method for manufacturing an integrated circuit, comprising:
forming a gate layer on a substrate, the gate layer having a first portion and a second portion;
doping the first portion of the gate layer with first dopants while leaving the second portion of the gate layer undoped with the first dopants;
patterning the first portion of the gate layer to form a first gate structure having a first cross-sectional profile;
patterning the second portion of the gate layer to form a second gate structure having a second cross-sectional profile different than the first cross-sectional profile;
forming a first epitaxial region adjacent a first sidewall of the first gate structure, wherein the first epitaxial region faces the first sidewall; and
forming a second epitaxial region adjacent a second sidewall of the second gate structure, wherein the second epitaxial region faces the second sidewall.
- 19.** The method of claim **18**, wherein at least one of:
the first cross-sectional profile is defined by a tapered sidewall of the first gate structure, or
the second cross-section profile is defined by a tapered sidewall of the second gate structure.
- 20.** The method of claim **18**, comprising:
forming a first spacer and a second spacer, wherein the first gate structure is disposed between the first spacer and the second spacer;
removing the first gate structure to define an opening; and forming a gate structure in the opening.

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